

SOT1781-2

WLCSP35, wafer level chip-size package; 35 terminals; 0.4 mm pitch; 3 mm x 2.16 mm x 0.525 mm body

29 April 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP35
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	23-11-2021
Manufacturer package code	98ASA01795D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	3	-	mm
package width	-	2.16	-	mm
seated height	-	0.525	0.565	mm
actual quantity of termination	-	35	-	



WLCSP35, wafer level chip-size package; 35 terminals; 0.4 mm pitch; 3 mm x 2.16 mm x 0.525 mm body

2 Package outline

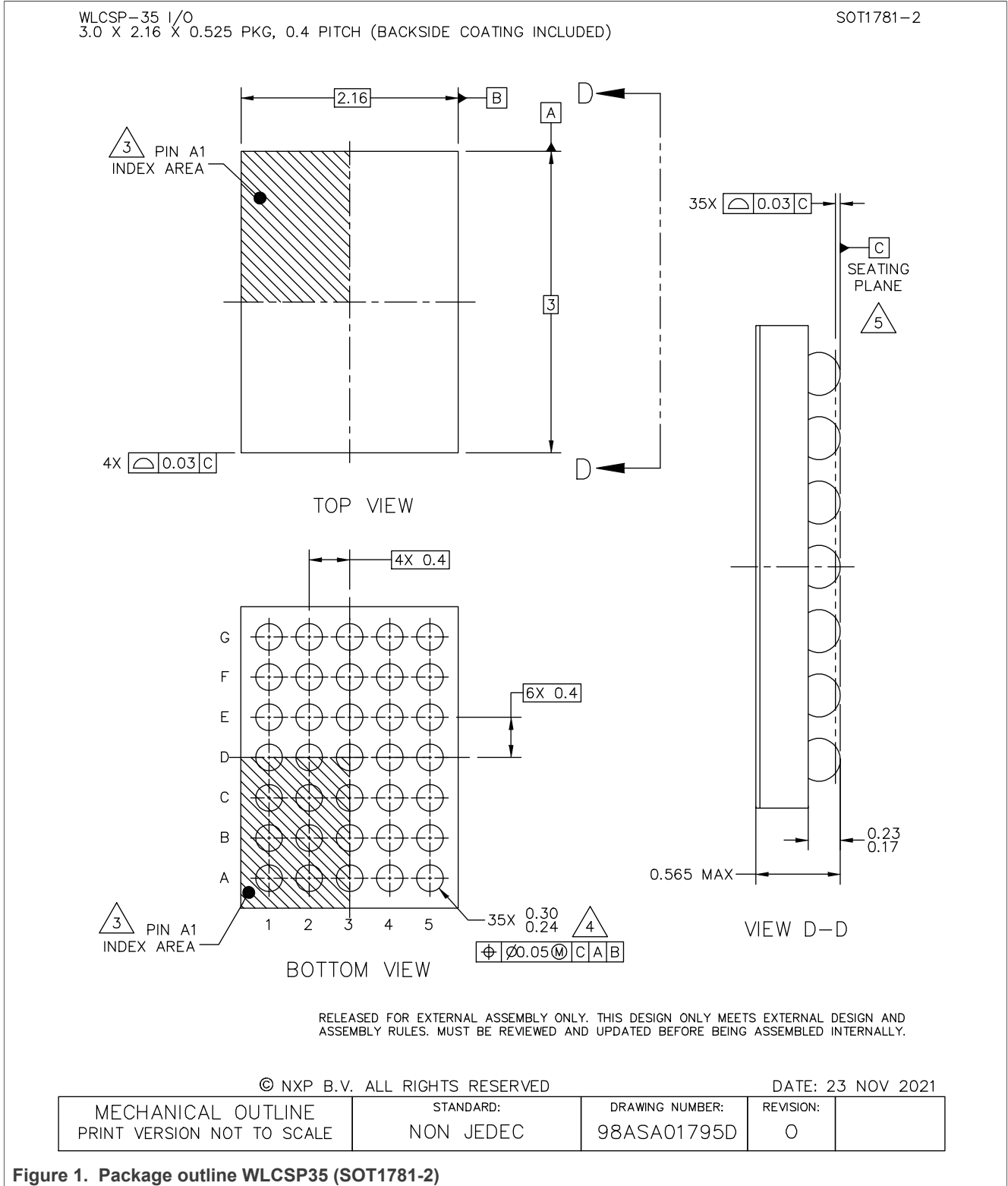


Figure 1. Package outline WLCSP35 (SOT1781-2)

WLCSP35, wafer level chip-size package; 35 terminals; 0.4 mm pitch; 3 mm x 2.16 mm x 0.525 mm body

3 Soldering

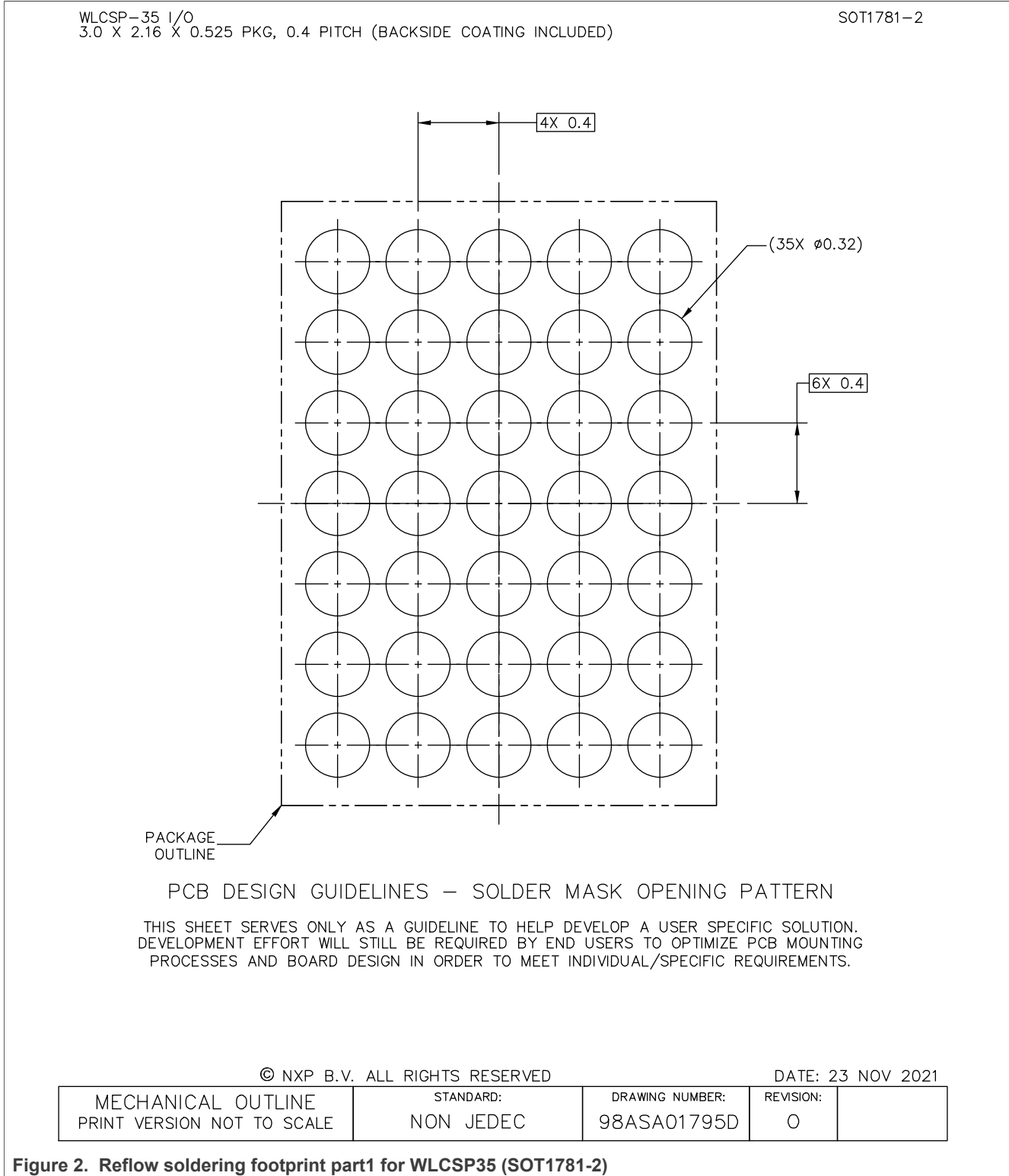
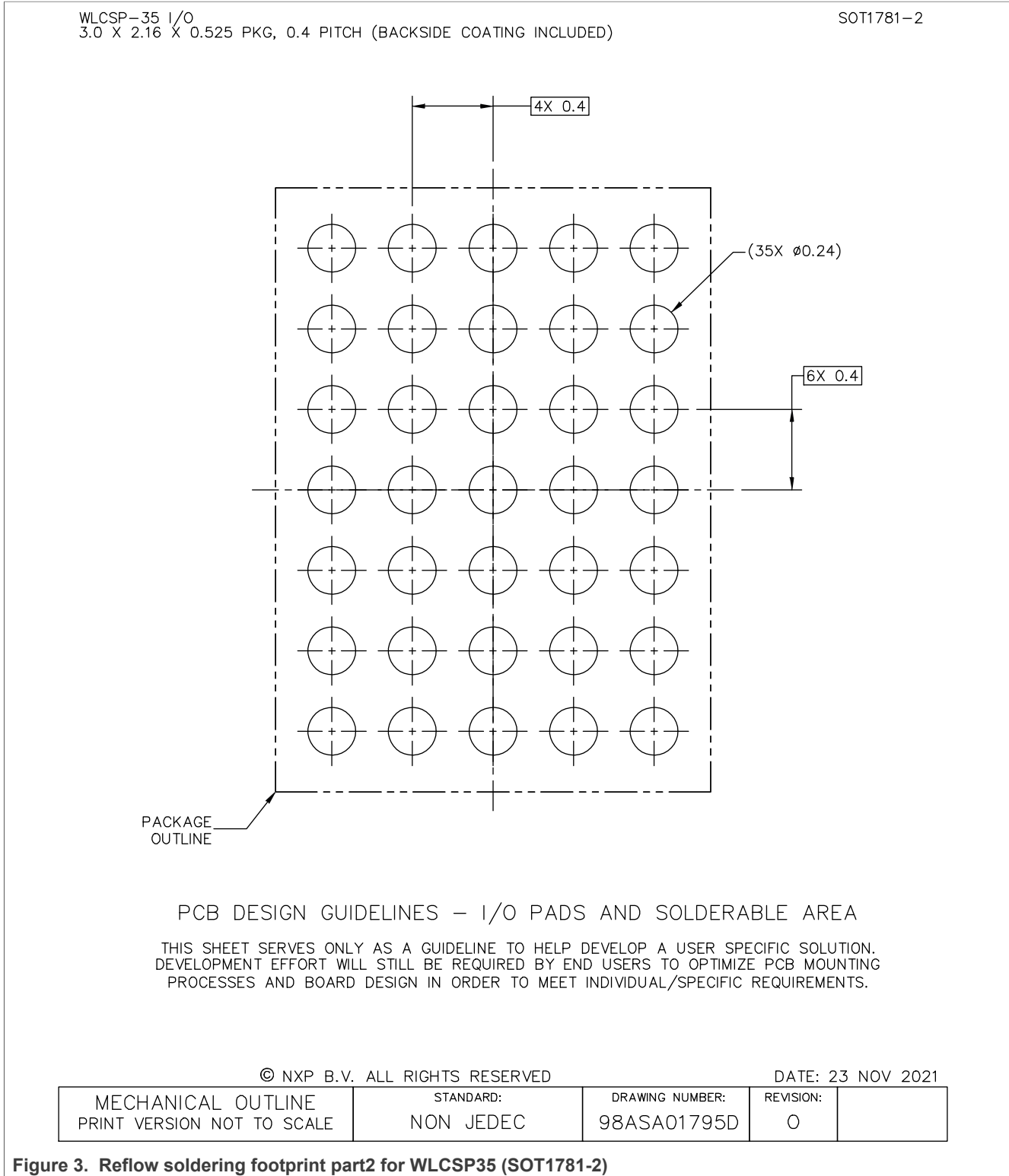


Figure 2. Reflow soldering footprint part1 for WLCSP35 (SOT1781-2)

WLCSP35, wafer level chip-size package; 35 terminals; 0.4 mm pitch; 3 mm x 2.16 mm x 0.525 mm body



WLCSP35, wafer level chip-size package; 35 terminals; 0.4 mm pitch; 3 mm x 2.16 mm x 0.525 mm body

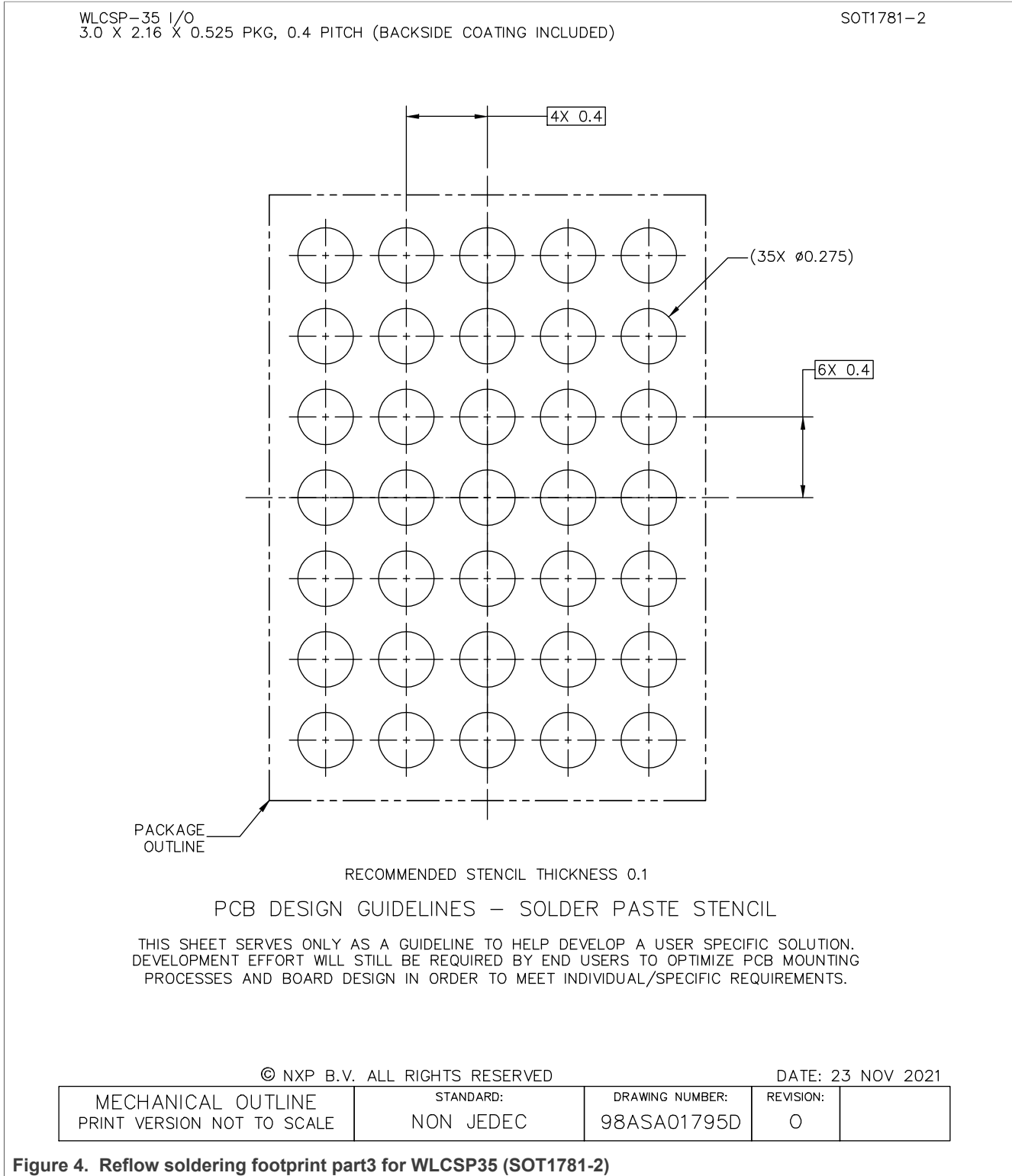


Figure 4. Reflow soldering footprint part3 for WLCSP35 (SOT1781-2)

WLCSP35, wafer level chip-size package; 35 terminals; 0.4 mm pitch; 3 mm x 2.16 mm x 0.525 mm body

WLCSP-35 I/O
3.0 X 2.16 X 0.525 PKG, 0.4 PITCH (BACKSIDE COATING INCLUDED)

SOT1781-2

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

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DATE: 23 NOV 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01795D	REVISION: 0	
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Figure 5. Package outline note WLCSP35 (SOT1781-2)

4 Legal information

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